Ultra-Low VF Schottky Rectifier, 10 A, 100 V

FSV10100V

Features

- Ultra−Low Forward Voltage Drop
- Low Thermal Resistance
- Very Low Profile: Typical Height of 1.1 mm
- Trench Schottky Technology
- Green Molding Compound as per IEC61249 Standard
- Non−DAP Option Only
- These Devices are Pb−Free, Halogen Free Free and are RoHS Compliant

Specifications

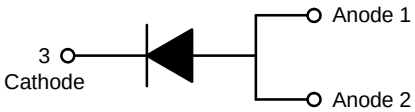
ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Rating	Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	100	V
V_{RWM}	Working Peak Reverse Voltage	100	V
V_{RMS}	RMS Reverse Voltage	70	V
V_R	DC Blocking Voltage	100	V
$I_{F(AV)}$	Average Rectified Peak Forward Surge Current	10	A
I_{FSM}	Non−Repetitive Peak Forward Surge Current	180	A
T_J	Operating Junction Temperature Range	−55 to +150	°C
T_{STG}	Storage Temperature Range	−55 to +150	°C

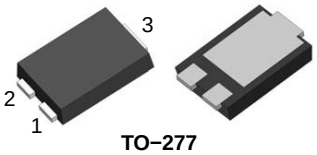
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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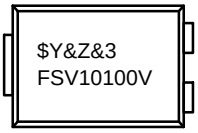


Schottky Rectifier



TO−277
CASE 340BQ

MARKING DIAGRAM



$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Date Code (Year & Week)
FSV10100V	= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Note 1)

Symbol	Characteristic	Minimum Land Pattern	Maximum Land Pattern	Unit
$R_{\theta JA}$	Junction−to−Ambient Thermal Resistance	100	40	°C/W
Ψ_{JL}	Junction−to−Lead Thermal Characteristics, Thermocouple Soldered to Anode	15	12	°C/W
	Junction−to−Lead Thermal Characteristics, Thermocouple Soldered to Cathode	6	5	

1. The thermal resistances ($R_{\theta JA}$ & Ψ_{JL}) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm. Minimum land pattern size: 4.9 x 4.8 mm (big pattern, x1), 1.4 x 1.52 mm (small pattern, x2). Maximum land pattern size: 30 x 30 mm (pattern, x2). Force line trace size = 55 mils, sense line trace size = 4 mils.



Figure 1. Minimum Land Pattern of 2 oz Copper

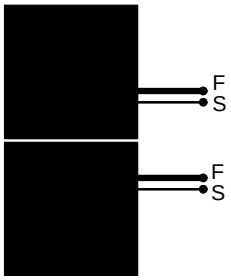


Figure 2. Maximum Land Pattern of 2 oz Copper

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BV_R	Breakdown Voltage	I_R = 0.5 mA	100	−	−	V
V_F	Forward Voltage Drop	I_F = 5 A	−	0.513	−	V
		I_F = 5 A, T_A = 125°C	−	0.463	−	
		I_F = 10 A	−	0.625	0.670	
		I_F = 10 A, T_A = 125°C	−	0.575	0.600	
I_R	Reverse Current	V_R = 70 V	−	0.0072	−	mA
		V_R = 70 V, T_A = 125°C	−	6.486	−	
		V_R = 100 V	−	0.0165	0.060	
		V_R = 100 V, T_A = 125°C	−	16.72	20	
C_J	Junction Capacitance	V_R = 4 V, f = 1 MHz	−	796	−	pF
T_{rr}	Reverse Recovery Time	I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A	−	22.94	−	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping†
FSV10100V	FSV10100V	TO−277 3L (Pb−Free/Halogen Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL PERFORMANCE CHARACTERISTICS

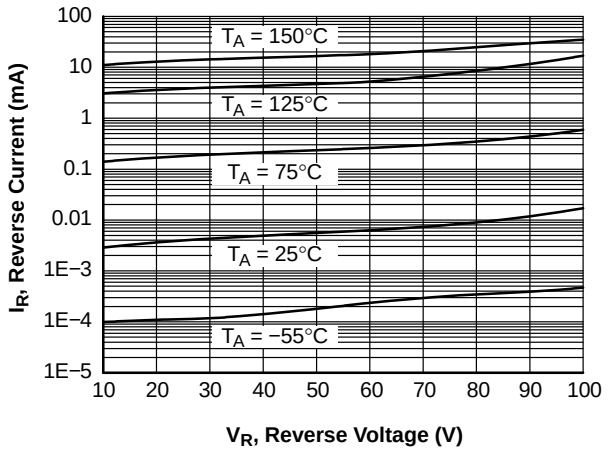


Figure 3. Typical Reverse Characteristics

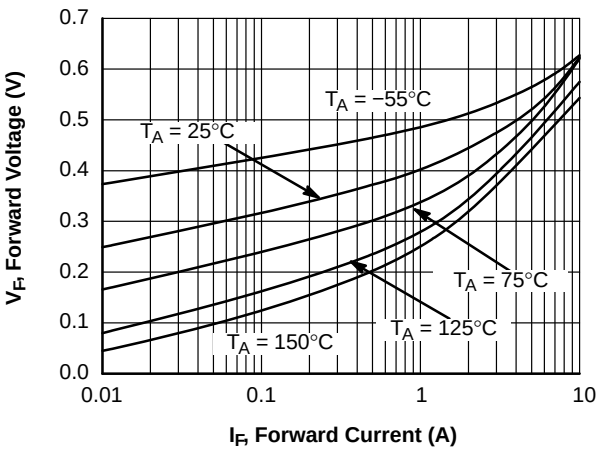


Figure 4. Typical Forward Characteristics

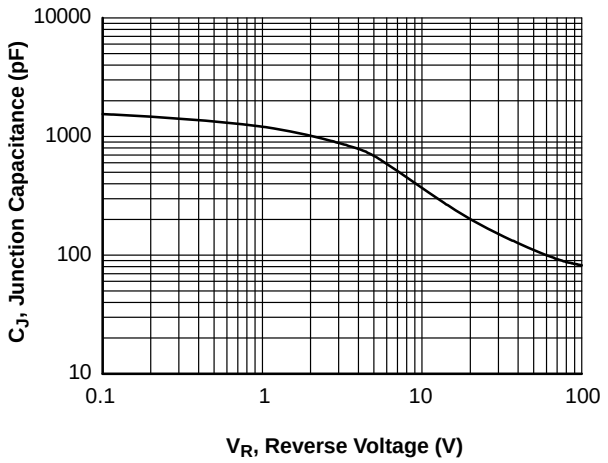


Figure 5. Typical Junction Capacitance

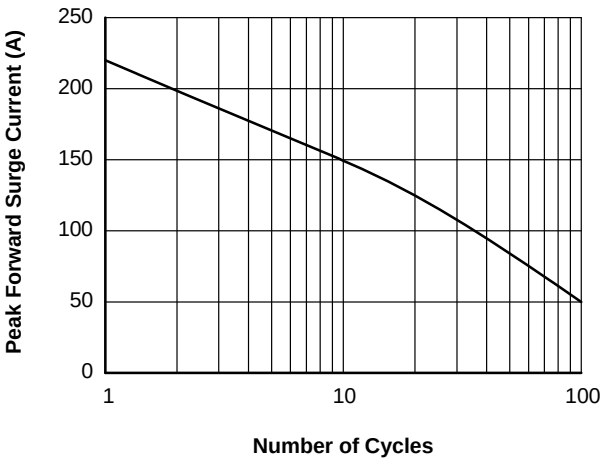


Figure 6. Maximum Non−Repetitive Peak Forward Surge Current

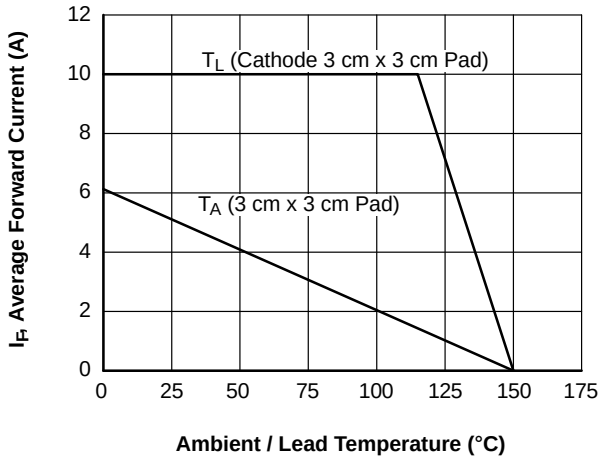
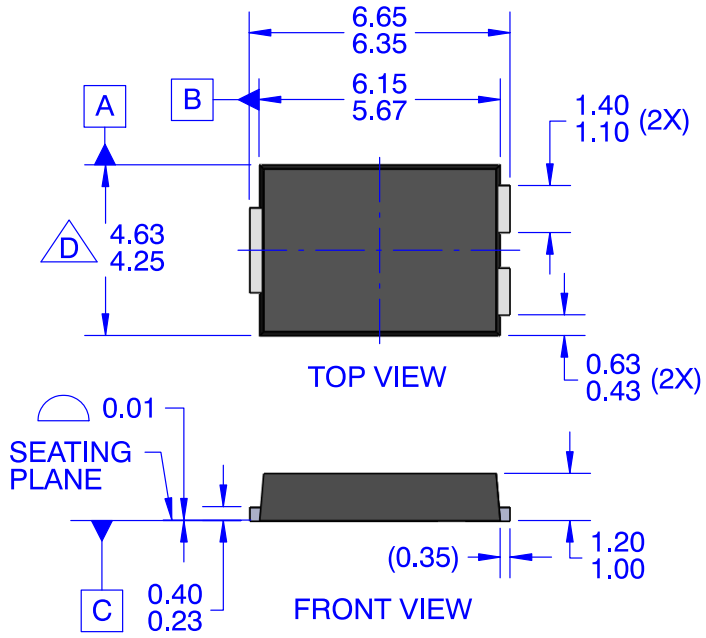
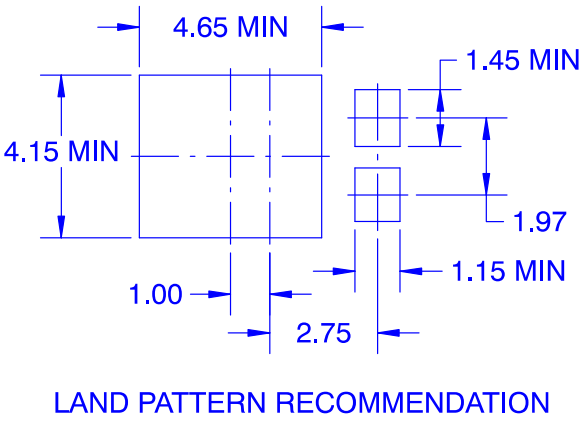


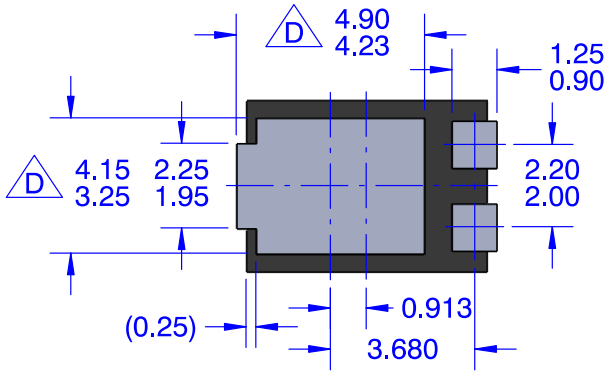
Figure 7. Forward Current Derating Curve

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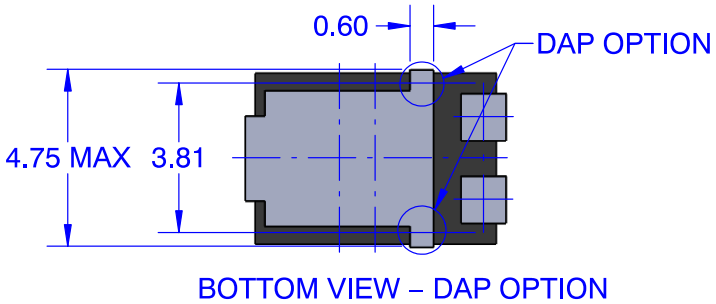




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